

Preliminary Amendment

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Title: ELECTRONIC COMPONENT WITH A HOUSING PACKAGE

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

~~Abstract~~**ELECTRONIC COMPONENT WITH A HOUSING PACKAGE****Abstract**

The invention relates to an electronic component with a housing package-(2) comprising a number of layers of plastic-(3) with at least one buried interconnect layer-(4) and with at least one semiconductor chip-(5), which has pointed-conical external contacts-(7) distributed on an outer side-(6). The pointed-conical external contacts-(7) penetrate through one of the layers of plastic-(3) and form contact vias with respect to the buried interconnect layer-(4). Furthermore, the invention relates to a method for producing such an electronic component-(1).

{~~Figure 1~~}